

Features

- CRM(CQ) Super_Junction technology
- Much lower Ron*A performance for On-state efficiency
- Better efficiency due to very low FOM
- Ultra-fast body diode

Applications

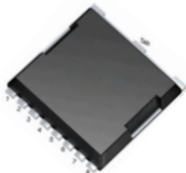
- LED/LCD/PDP TV and monitor Lighting
- Solar/Renewable/UPS-Micro Inverter System
- Charger
- Power Supply

Product Summary

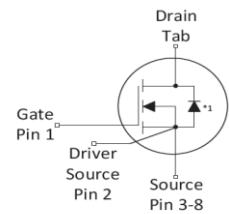
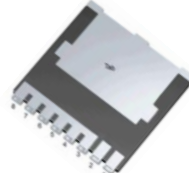
| | |
|------------------|------|
| $V_{DS,min}$ | 600V |
| $R_{DS(on),typ}$ | 70mΩ |
| I_D | 34A |

100% DVDS Tested
100% Avalanche Tested


Top view



Bottom view



*1: Internal body diode

Package Marking and Ordering Information

| Part # | Marking | Package | Packing | Reel Size | Tape Width | Qty |
|--------------|------------|---------|-----------|-----------|------------|---------|
| CRJZ74N60G2F | JZ74N60G2F | TOLL | Tape&Reel | N/A | N/A | 2000pcs |

Absolute Maximum Ratings

| Parameter | Symbol | Value | Unit |
|---|----------------|------------|------|
| Drain-source voltage | V_{DS} | 600 | V |
| Continuous drain current ¹⁾ $T_C = 25^\circ\text{C}$ $T_C = 100^\circ\text{C}$ | I_D | 34 21 | A |
| Pulsed drain current ²⁾ ($T_C = 25^\circ\text{C}$, t_p limited by $T_{j,max}$) | $I_{D,pulse}$ | 101 | A |
| Avalanche energy, single pulse ($L=30\text{mH}$) | E_{AS} | 520 | mJ |
| MOSFET dv/dt ruggedness | dv/dt | 50 | V/ns |
| Gate-Source voltage | V_{GS} | ±30 | V |
| Power dissipation ($T_C = 25^\circ\text{C}$) | P_{tot} | 237 | W |
| Continuous diode forward current($T_C = 25^\circ\text{C}$) | I_S | 34 | A |
| Diode pulse current ²⁾ ($T_C = 25^\circ\text{C}$) | $I_{S,pulse}$ | 101 | A |
| Recovery diode dv/dt ³⁾ | dv/dt | 50 | V/ns |
| Operating junction and storage temperature | T_j, T_{stg} | -55...+150 | °C |

 1) Limited by $T_{j,max}$. Maximum Duty Cycle $D = 0.50$

 2) Pulse width t_p limited by $T_{j,max}$

 3) Identical low side and high side switch with identical R_g

Thermal Resistance

| Parameter | Symbol | Value | | | Unit | Test Condition |
|--|------------|-------|------|------|------|----------------|
| | | min. | typ. | max. | | |
| Thermal resistance, junction – case | R_{thJC} | - | 0.38 | 0.53 | °C/W | |
| Thermal resistance, junction – ambient | R_{thJA} | - | - | 53 | °C/W | |

Electrical Characteristic (at $T_j = 25\text{ }^\circ\text{C}$, unless otherwise specified)

| Parameter | Symbol | Value | | | Unit | Test Condition |
|-----------|--------|-------|------|------|------|----------------|
| | | min. | typ. | max. | | |

Static Characteristic

| | | | | | | |
|----------------------------------|--------------|-----|----|-----------|---------|---|
| Drain-source breakdown voltage | BV_{DSS} | 600 | - | - | V | $V_{GS}=0V, I_D=250\mu A$ |
| Gate threshold voltage | $V_{GS(th)}$ | 3.2 | - | 4.6 | V | $V_{DS}=V_{GS}, I_D=250\mu A$ |
| Zero gate voltage drain current | I_{DSS} | - | - | 5 | μA | $V_{DS}=600V, V_{GS}=0V$ $T_j=25^\circ C$ $T_j=150^\circ C$ |
| Gate-source leakage current | I_{GSS} | - | - | ± 100 | nA | $V_{GS}=\pm 30V, V_{DS}=0V$ |
| Drain-source on-state resistance | $R_{DS(on)}$ | - | 70 | 77 | mΩ | $V_{GS}=10V, I_D=23A,$ $T_j=25^\circ C$ $T_j=150^\circ C$ |
| Transconductance | g_{fs} | - | 28 | - | S | $V_{DS}=20V, I_D=23A$ |

Dynamic Characteristic

| | | | | | | |
|------------------------------|---------------|---|------|---|----|---|
| Input Capacitance | C_{iss} | - | 2400 | - | pF | $V_{GS}=0V, V_{DS}=100V,$ $f=1MHz$ |
| Output Capacitance | C_{oss} | - | 144 | - | | |
| Reverse Transfer Capacitance | C_{rss} | - | 2.5 | - | | |
| Gate Total Charge | Q_g | - | 65 | - | nC | $V_{GS}=10V, V_{DS}=480V,$ $I_D=23A$ |
| Gate-Source charge | Q_{gs} | - | 22 | - | | |
| Gate-Drain charge | Q_{gd} | - | 35 | - | | |
| Gate plateau voltage | $V_{plateau}$ | - | 8.1 | - | V | |
| Turn-on delay time | $t_{d(on)}$ | - | 65 | - | ns | $V_{GS}=10V, I_D=23A,$ $V_{DS}=400V, R_g=27\Omega$ |
| Rise time | t_r | - | 91 | - | | |
| Turn-off delay time | $t_{d(off)}$ | - | 150 | - | | |
| Fall time | t_f | - | 40 | - | | |
| Gate resistance | $R_{g,int}$ | - | 1.2 | - | Ω | $f=1MHz$ |

Body Diode Characteristic

| Parameter | Symbol | Value | | | Unit | Test Condition |
|------------------------------------|----------|-------|------|------|---------|--------------------------------------|
| | | min. | typ. | max. | | |
| Body Diode Forward Voltage | V_{SD} | 0.7 | 0.91 | 1.1 | V | $V_{GS}=0V, I_{SD}=23A$ |
| Body Diode Reverse Recovery Time | t_{rr} | - | 125 | | ns | $I_{SD}=23A$ $di_F/dt=100A/\mu s$ |
| Body Diode Reverse Recovery Charge | Q_{rr} | - | 0.9 | | μC | $V_{DS}=400V$ |

Typical Performance Characteristics

Fig 1. Output Characteristics ($T_j=25^\circ\text{C}$)

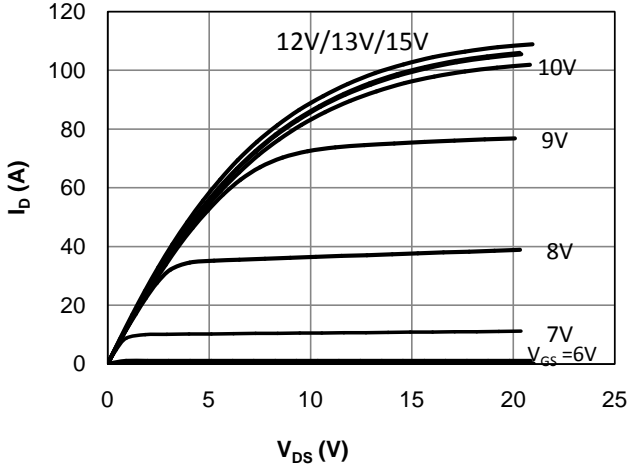


Fig 2. Output Characteristics ($T_j=150^\circ\text{C}$)

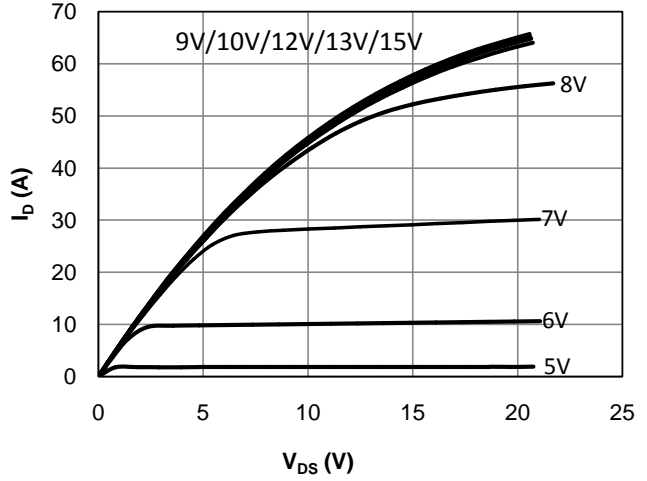


Fig 3: Transfer Characteristics

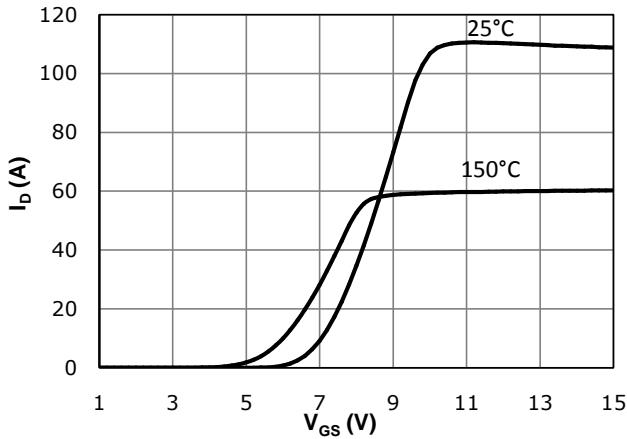


Fig 4: V_{TH} vs. T_j Temperature Characteristics

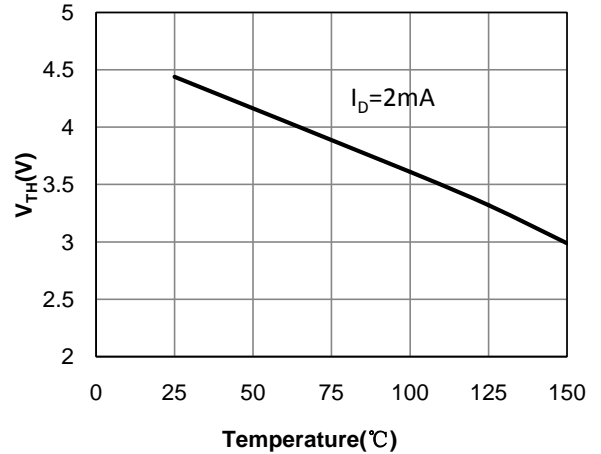


Fig 5: $R_{DS(on)}$ vs. I_{DS} Characteristics ($T_j=25^\circ\text{C}$)

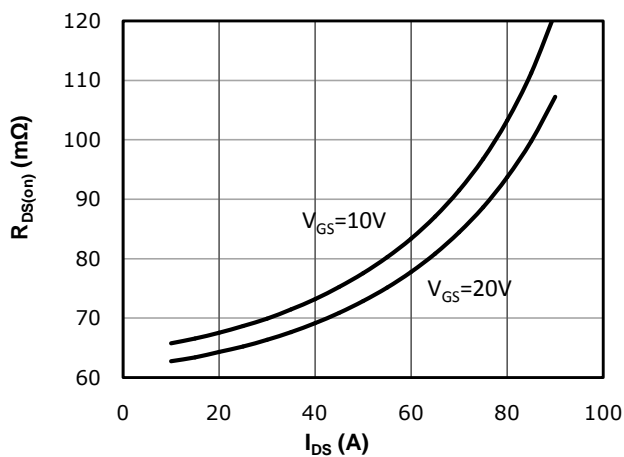


Fig 6: $R_{DS(on)}$ vs. Temperature

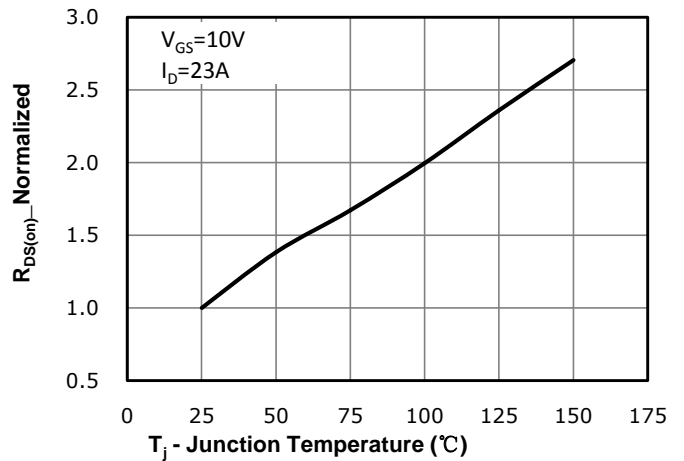


Fig 7: BV_{DSS} vs. Temperature

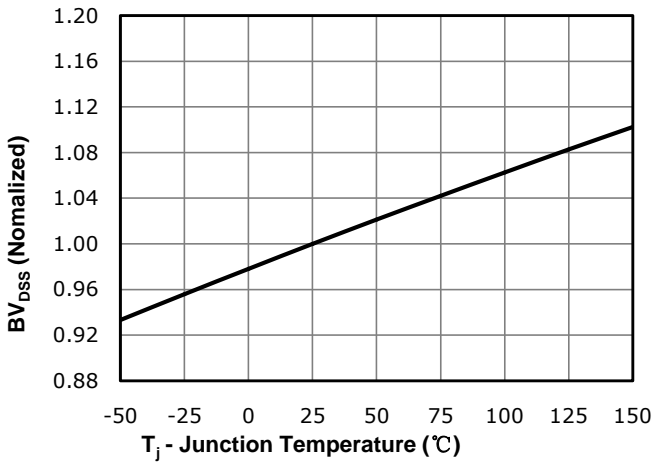


Fig 8: $R_{DS(on)}$ vs. Gate Voltage

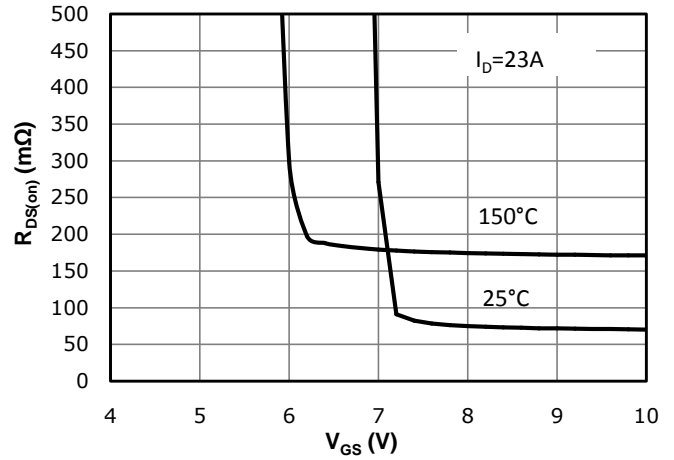


Fig 9: Body-diode Forward Characteristics

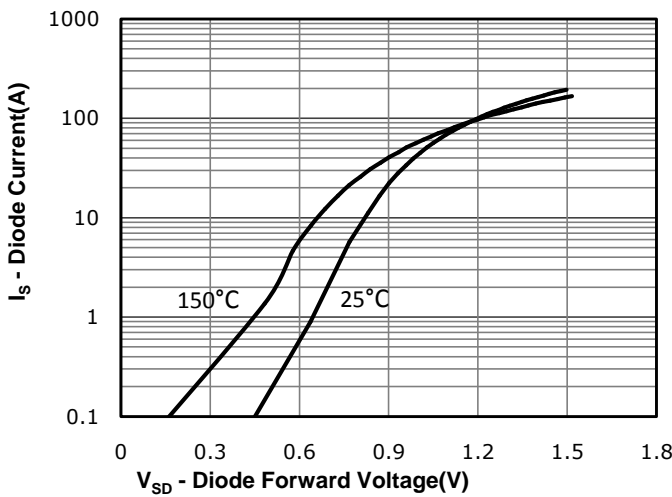


Fig 10: Gate Charge Characteristics

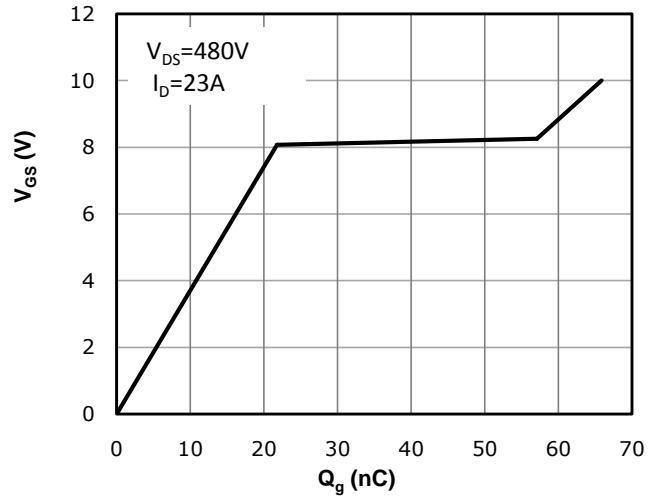


Fig 11: Capacitance Characteristics

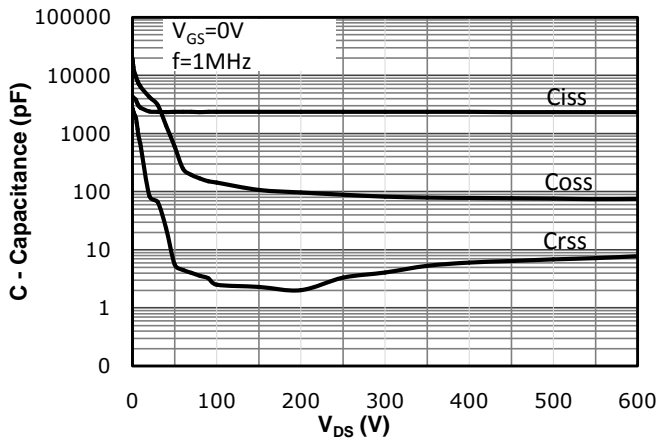


Fig 12: Safe Operating Area

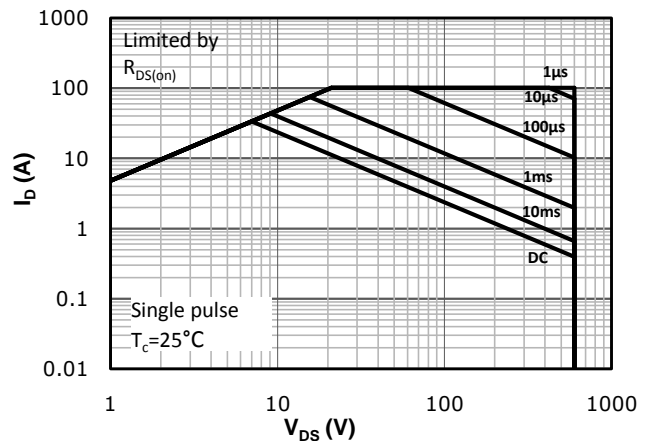
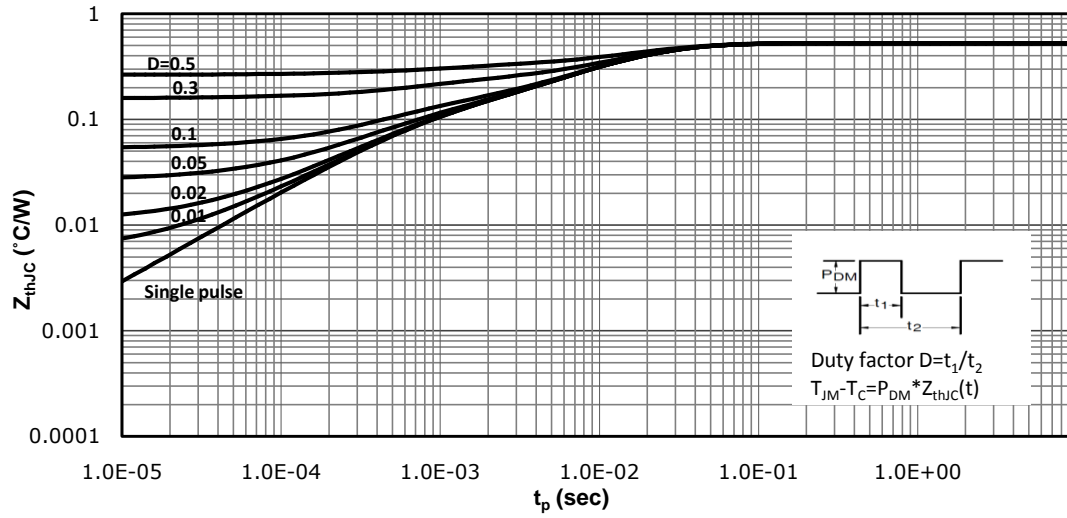
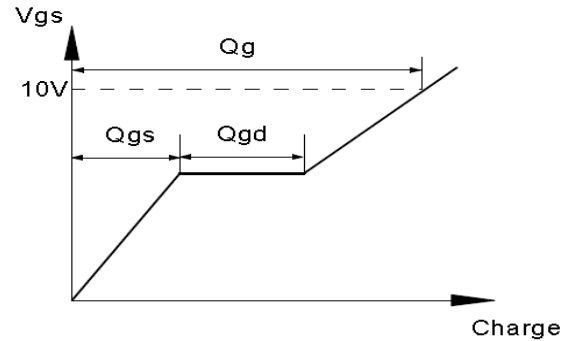
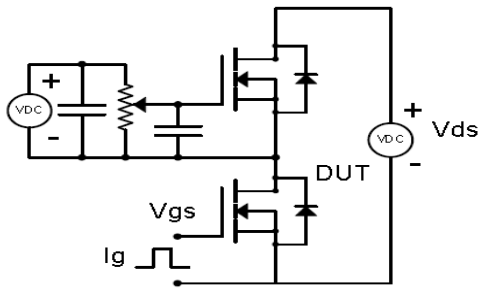


Fig 13: Max. Transient Thermal Impedance

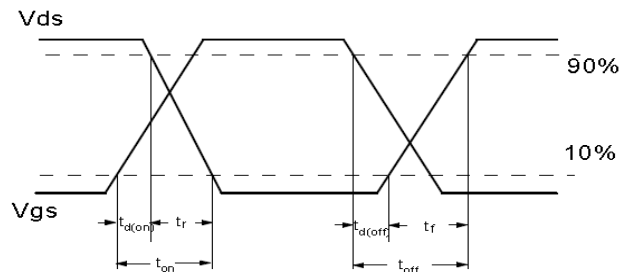
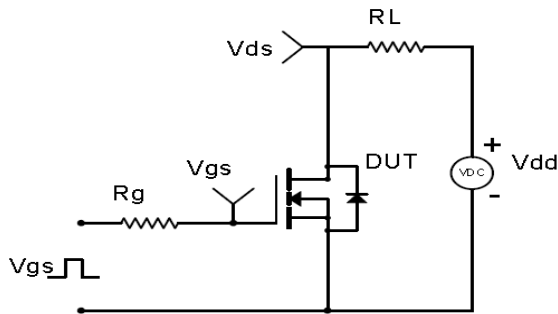


Test Circuit & Waveform

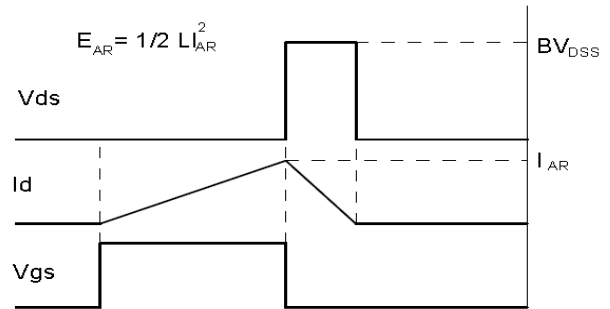
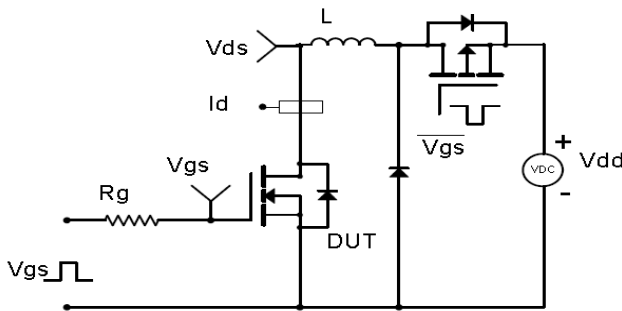
Gate Charge Test Circuit & Waveform



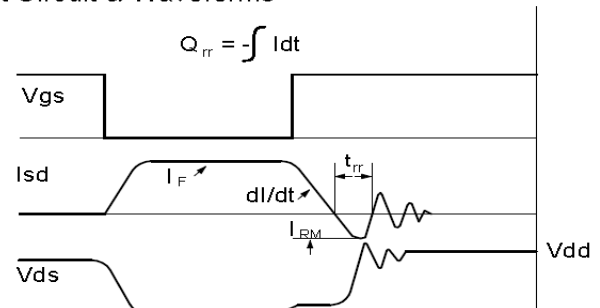
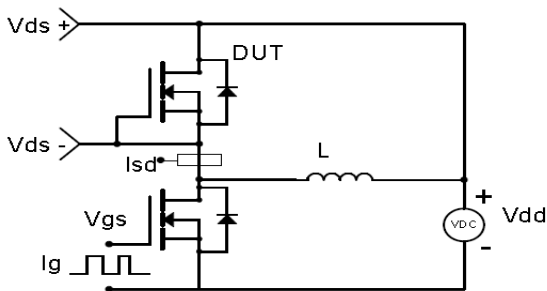
Resistive Switching Test Circuit & Waveforms

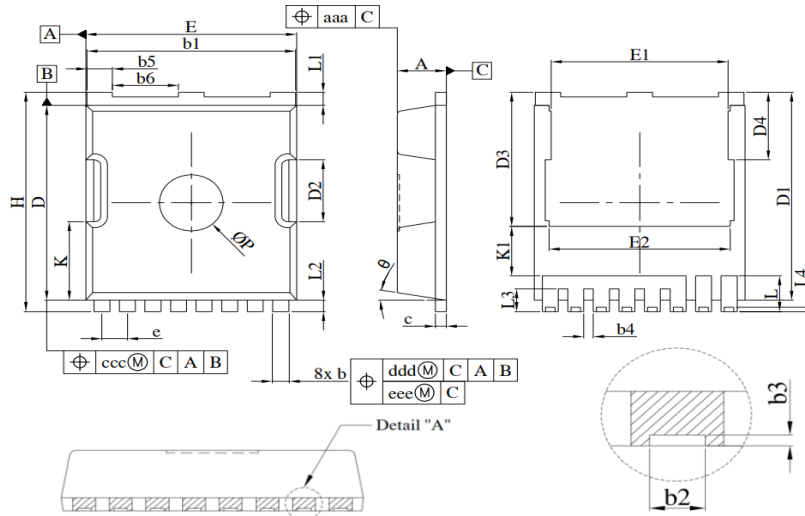


Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



Package Outline: TOLL


| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------|----------------------|-------|
| | Min. | Max. | Min. | Max. |
| A | 2.20 | 2.40 | 0.087 | 0.094 |
| b | 0.70 | 0.90 | 0.028 | 0.035 |
| b1 | 9.70 | 9.90 | 0.382 | 0.390 |
| b2 | 0.36 | 0.55 | 0.014 | 0.022 |
| b3 | 0.05 | 0.35 | 0.002 | 0.014 |
| b4 | 0.30 | 0.50 | 0.012 | 0.020 |
| b5 | 1.10 | 1.30 | 0.043 | 0.051 |
| b6 | 3.00 | 3.20 | 0.118 | 0.126 |
| c | 0.40 | 0.60 | 0.016 | 0.024 |
| D | 10.28 | 10.55 | 0.405 | 0.415 |
| D1 | 10.98 | 11.18 | 0.432 | 0.440 |
| D2 | 3.20 | 3.40 | 0.126 | 0.134 |
| D3 | 7.00 | 7.30 | 0.276 | 0.287 |
| D4 | 3.44 | 3.74 | 0.135 | 0.147 |
| e | 1.10 | 1.30 | 0.043 | 0.051 |
| E | 9.80 | 10.00 | 0.386 | 0.394 |
| E1 | 8.20 | 8.40 | 0.323 | 0.331 |
| E2 | 8.35 | 8.65 | 0.329 | 0.341 |
| H | 11.50 | 11.85 | 0.453 | 0.467 |
| K | 4.08 | 4.28 | 0.161 | 0.169 |
| K1 | 2.45 | --- | 0.096 | --- |
| L | 1.60 | 2.10 | 0.063 | 0.083 |
| L1 | 0.50 | 0.90 | 0.020 | 0.035 |
| L2 | 0.50 | 0.70 | 0.020 | 0.028 |
| L3 | 1.00 | 1.30 | 0.039 | 0.051 |
| L4 | 0.13 | 0.33 | 0.005 | 0.013 |
| P | 2.85 | 3.15 | 0.112 | 0.124 |
| θ | 10°REF | | | |
| aaa | 0.20 | | 0.008 | |
| ccc | 0.20 | | 0.008 | |
| ddd | 0.25 | | 0.010 | |
| eee | 0.20 | | 0.008 | |

Marking



NOTE:

NXBBAAAA

N —WB code (Usually omitted)

X —Assembly location code

BB —Fab code

AAAA —Lot code

Revision History

| Revision | Date | Major changes |
|----------|------------|---------------|
| 1.0 | 2023/10/11 | First version |

Disclaimer

Unless otherwise specified in the datasheet, the product is designed and qualified as a standard commercial product and is not intended for use in applications that require extraordinary levels of quality and reliability, such as automotive, aviation/aerospace and life-support devices or systems.

Any and all semiconductor products have certain probability to fail or malfunction, which may result in personal injury, death or property damage. Customer are solely responsible for providing adequate safe measures when design their systems.

CRM(CQ) reserves the right to improve product design, function and reliability without notice.